

## Addendum

HC908JB8AD/D  
Rev. 0, 4/2002

Addendum to  
MC68HC908JB8  
Technical Data



This addendum provides additional information to the  
*MC68HC908JB8 Technical Data, Rev. 2*  
(Motorola document number MC68HC908JB8/D),

## MC68HC08JB8A

The MC68HC08JB8A is the ROM part equivalent to the MC68HC908JB8. The entire MC68HC908JB8 data book apply to this ROM device, with exceptions outlined in this addendum.

**Table 1. Summary of MC68HC08JB8A and MC68HC908JB8 Differences**

	MC68HC08JB8A	MC68HC908JB8
<b>Memory (\$DC00–\$FBFF)</b>	8,192 bytes ROM	8,192 bytes FLASH
<b>User vectors (\$FFF0–\$FFFF)</b>	16 bytes ROM	16 bytes FLASH
<b>Registers at \$FE08 and \$FF09</b>	Not used; locations are reserved.	FLASH related registers. \$FE08 — FLCR \$FF09 — FLBPR
<b>Monitor ROM (\$FC00–\$FDFF and \$FE10–\$FFDF)</b>	\$FC00–\$FDFF: Not used. \$FE10–\$FFDF: Used for testing purposes only.	Used for testing and FLASH programming/erasing.
<b>OSC1 and OSC2 pins</b>	V <sub>DD</sub> level (5V logic)	V <sub>REG</sub> level (3.3V logic)

**MCU Block Diagram** **Figure 1** shows the block diagram of the MC68HC08JB8A.

**Memory Map** The MC68HC08JB8A has 8,192 bytes of user ROM from \$DC00 to \$FBFF, and 16 bytes of user ROM vectors from \$FFF0 to \$FFFF. On the MC68HC908JB8, these memory locations are FLASH memory.

**Figure 2** shows the memory map of the MC68HC08JB8A.

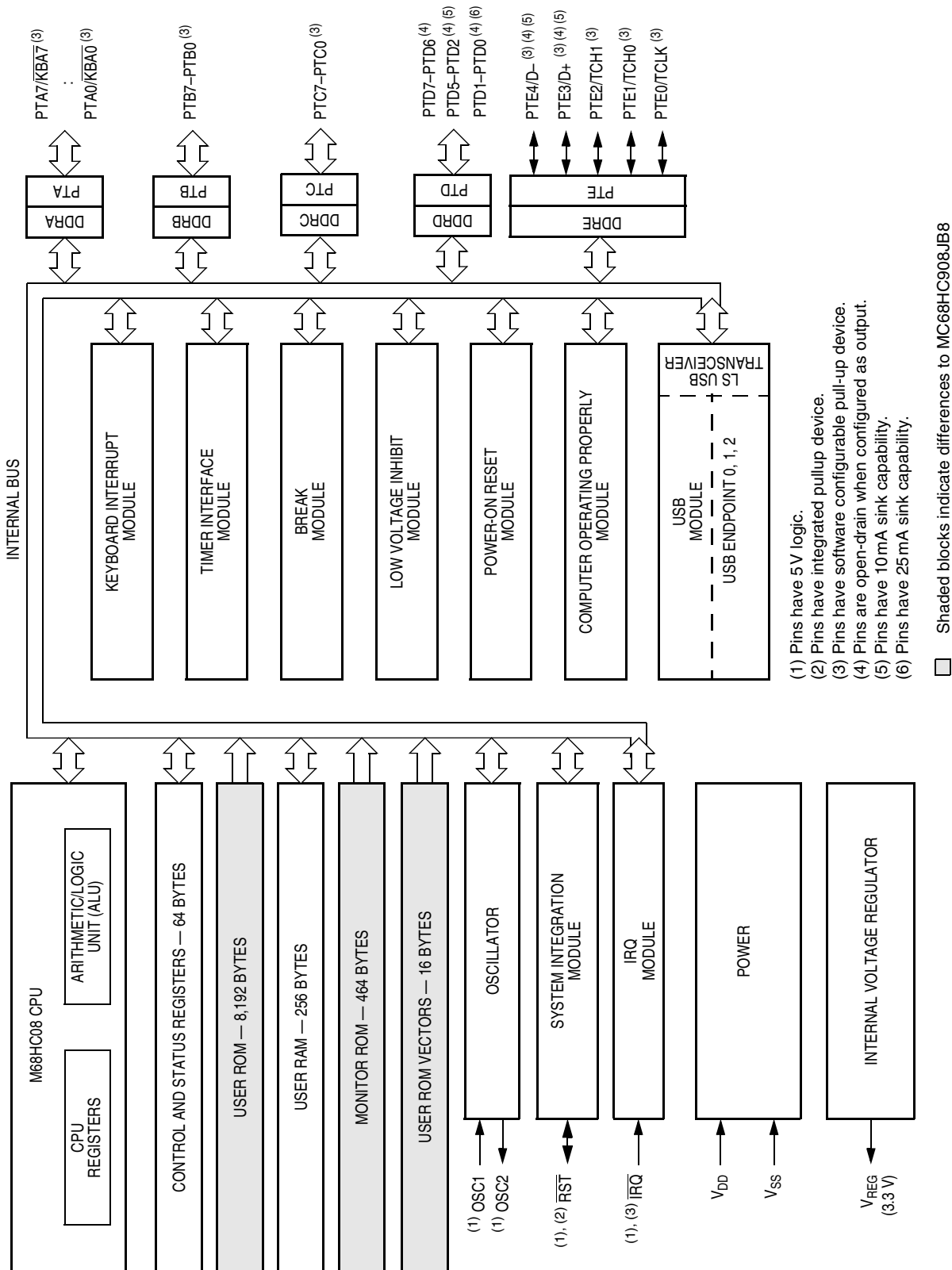


Figure 1. MC68HC08JB8A Block Diagram

\$0000 ↓ \$003F	I/O Registers 64 Bytes
\$0040 ↓ \$013F	RAM 256 Bytes
\$0140 ↓ \$DBFF	Unimplemented 56,000 Bytes
\$DC00 ↓ \$FBFF	ROM 8,192 Bytes
\$FC00 ↓ \$FDFF	Unimplemented 512 Bytes
\$FE00	Break Status Register (BSR)
\$FE01	Reset Status Register (RSR)
\$FE02	Reserved
\$FE03	Break Flag Control Register (BFCR)
\$FE04	Interrupt Status Register 1 (INT1)
\$FE05	Reserved
\$FE06	Reserved
\$FE07	Reserved
\$FE08	Reserved
\$FE09	Reserved
\$FE0A	Reserved
\$FE0B	Reserved
\$FE0C	Break Address High Register (BRKH)
\$FE0D	Break Address Low Register (BRKL)
\$FE0E	Break Status and Control Register (BRKSCR)
\$FE0F	Reserved
\$FE10 ↓ \$FFDF	Monitor ROM 464 Bytes
\$FFE0 ↓ \$FFEF	Reserved 16 Bytes
\$FFF0 ↓ \$FFFF	ROM Vectors 16 Bytes

**Figure 2. MC68HC08JB8A Memory Map**

### Reserved Registers

The two registers at \$FE08 and \$FE09 are reserved locations on the MC68HC08JB8A.

On the MC68HC908JB8, these two locations are the FLASH control register and the FLASH block protect register respectively.

### Monitor ROM

The monitor program (monitor ROM: \$FE10–\$FFDF) on the MC68HC08JB8A is for device testing only. \$FC00–\$FDFF are unused.

### Electrical Specifications

Electrical specifications for the MC68HC908JB8 apply to the MC68HC08JB8A, except for the parameters indicated below.

#### DC Electrical Characteristics

**Table 2. DC Electrical Characteristics**

Characteristic <sup>(1)</sup>	Symbol	Min	Typ <sup>(2)</sup>	Max	Unit
Regulator output voltage	V <sub>REG</sub>	3.0	3.3	3.6	V
Output high voltage (I <sub>Load</sub> = –2.0 mA) PTA0–PTA7, PTB0–PTB7, PTC0–PTC7, PTE0–PTE2	V <sub>OH</sub>	V <sub>REG</sub> –0.8	—	—	V
Output low voltage (I <sub>Load</sub> = 1.6 mA) All I/O pins (I <sub>Load</sub> = 25 mA) PTD0–PTD1 in ILDD mode (I <sub>Load</sub> = 10 mA) PTE3–PTE4 with USB disabled	V <sub>OL</sub>	— — —	— — —	0.4 0.5 0.4	V
Input high voltage All ports, OSC1 $\overline{\text{IRQ}}$ , $\overline{\text{RST}}$	V <sub>IH</sub>	0.7 × V <sub>REG</sub> 0.7 × V <sub>DD</sub>	— —	V <sub>REG</sub> V <sub>DD</sub>	V
Input low voltage All ports, OSC1 $\overline{\text{IRQ}}$ , $\overline{\text{RST}}$	V <sub>IL</sub>	V <sub>SS</sub> V <sub>SS</sub>	— —	0.3 × V <sub>REG</sub> 0.3 × V <sub>DD</sub>	V
Output low current (V <sub>OL</sub> = 2.0 V) PTD2–PTD5 in LDD mode	I <sub>OL</sub>	12 (17)	17 (22)	22 (27)	mA
V <sub>DD</sub> supply current, V <sub>DD</sub> = 5.25V, f <sub>OP</sub> = 3MHz Run, with low speed USB <sup>(3)</sup> Run, with USB suspended <sup>(3)</sup> Wait, with low speed USB <sup>(4)</sup> Wait, with USB suspended <sup>(4)</sup> Stop <sup>(5)</sup> 0 °C to 70°C	I <sub>DD</sub>	— — — — —	6.0 (5.0) 5.5 (4.5) 4.0 (3.0) 3.0 (2.5) 30	7.5 6.5 5.0 4.0 100	mA mA mA mA μA

Table 2. DC Electrical Characteristics

Characteristic <sup>(1)</sup>	Symbol	Min	Typ <sup>(2)</sup>	Max	Unit
I/O ports Hi-Z leakage current	$I_{IL}$	—	—	$\pm 10$	$\mu A$
Input current	$I_{IN}$	—	—	$\pm 1$	$\mu A$
Capacitance Ports (as input or output)	$C_{Out}$ $C_{In}$	— —	— —	12 8	pF
POR re-arm voltage <sup>(6)</sup>	$V_{POR}$	0	—	100	mV
POR rise-time ramp rate <sup>(7)</sup>	$R_{POR}$	0.035	—	—	V/ms
Monitor mode entry voltage	$V_{DD}+V_{HI}$	$1.4 \times V_{DD}$		$2 \times V_{DD}$	V
Pullup resistors Port A, port B, port C, PTE0–PTE2, $\overline{RST}$ , $\overline{IRQ}$ PTE3–PTE4 (with USB module disabled) D– (with USB module enabled)	$R_{PU}$	25 4 1.2	40 5 1.5	55 6 2.0	k $\Omega$
LVI reset	$V_{LVR}$	2.8 (2.4)	3.3 (2.7)	3.8 (3.0) <sup>(8)</sup>	V

- $V_{DD} = 4.0$  to  $5.5$  Vdc,  $V_{SS} = 0$  Vdc,  $T_A = T_L$  to  $T_H$ , unless otherwise noted.
- Typical values reflect average measurements at midpoint of voltage range,  $25^\circ C$  only.
- Run (operating)  $I_{DD}$  measured using external square wave clock source ( $f_{XCLK} = 6$  MHz). All inputs 0.2 V from rail. No dc loads. Less than 100 pF on all outputs.  $C_L = 20$  pF on OSC2. All ports configured as inputs. OSC2 capacitance linearly affects run  $I_{DD}$ . Measured with all modules enabled.
- Wait  $I_{DD}$  measured using external square wave clock source ( $f_{XCLK} = 6$  MHz); all inputs 0.2 V from rail; no dc loads; less than 100 pF on all outputs.  $C_L = 20$  pF on OSC2; 15 k $\Omega \pm 5\%$  termination resistors on D+ and D– pins; all ports configured as inputs; OSC2 capacitance linearly affects wait  $I_{DD}$ .
- STOP  $I_{DD}$  measured with USB in suspend mode; OSC1 grounded; transceiver pullup resistor of 1.5 k $\Omega \pm 5\%$  between  $V_{REG}$  and D– pins and 15 k $\Omega \pm 5\%$  termination resistor on D+ pin; no port pins sourcing current.
- Maximum is highest voltage that POR is guaranteed.
- If minimum  $V_{REG}$  is not reached before the internal POR reset is released,  $\overline{RST}$  must be driven low externally until minimum  $V_{REG}$  is reached.
- The numbers in parenthesis are MC68HC08JB8 (non-A part) values.

## Memory Characteristics

Table 3. Memory Characteristics

Characteristic	Symbol	Min	Max	Unit
RAM data retention voltage	$V_{RDR}$	1.3	—	V

### Notes:

Since MC68HC08JB8A is a ROM device, FLASH memory electrical characteristics do not apply.

### MC68HC08JB8A Order Numbers

These part numbers are generic numbers only. To place an order, ROM code must be submitted to the ROM Processing Center (RPC).

**Table 4. MC68HC08JB8A Order Numbers**

MC order number	Package	Operating temperature range
MC68HC08JB8AJP	20-pin PDIP	0 °C to +70 °C
MC68HC08JB8AJDW	20-pin SOIC	0 °C to +70 °C
MC68HC08JB8AADW	28-pin SOIC	0 °C to +70 °C
MC68HC08JB8AFB	44-pin QFP	0 °C to +70 °C

### MC68HC08JB8A and MC68HC08JB8 Differences

The MC68HC08JB8A and MC68HC08JB8 are identical devices, except for the following:

**Table 5. MC68HC08JB8A and MC68HC08JB8 Differences**

	MC68HC08JB8A	MC68HC08JB8
OSC1 and OSC2 pins	V <sub>DD</sub> level (5V logic)	V <sub>REG</sub> level (3.3V logic)
Output low current on PTD2–PTD5 in LDD mode	See <a href="#">Table 2 . DC Electrical Characteristics</a> . The numbers in parenthesis are MC68HC08JB8 values.	
Operating I <sub>DD</sub> currents		
LVI trip points		

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**NOTES**

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